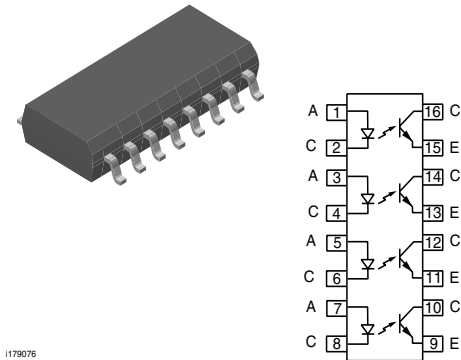




Optocoupler, Phototransistor Output, Quad Channel, SOP-16, Half Pitch Mini-Flat Package

Features

- SOP (Small Outline Package)
- Isolation Test Voltage, 3750 V_{RMS} (1.0 s)
- High Collector-Emitter Voltage, V_{CEO} = 70 V
- Low Saturation Voltage
- Fast Switching Times
- Temperature Stable
- Low Coupling Capacitance
- End-Stackable, 0.050 " (1.27 mm) Spacing



Agency Approvals

- UL File #E52744 System Code U

The coupling devices are designed for signal transmission between two electrically separated circuits.

Description

The SFH6916 has a GaAs infrared emitter, which is optically coupled to a silicon planar phototransistor detector, and is incorporated in a 16-pin 50 mil lead pitch miniflat package. It features a high current transfer ratio, low coupling capacitance, and high isolation voltage.

Order Information

Part	Remarks
SFH6916	CTR 50 - 300 %, SMD-16

For additional information on the available options refer to Option Information.

Absolute Maximum Ratings

T_{amb} = 25 °C, unless otherwise specified

Stresses in excess of the absolute Maximum Ratings can cause permanent damage to the device. Functional operation of the device is not implied at these or any other conditions in excess of those given in the operational sections of this document. Exposure to absolute Maximum Rating for extended periods of the time can adversely affect reliability.

Input

Parameter	Test condition	Symbol	Value	Unit
Reverse voltage		V _R	6.0	V
DC Forward current		I _F	50	mA
Surge forward current	t _p ≤ 10 μs	I _{FSM}	2.5	A
Total power dissipation		P _{diss}	80	mW

Output

Parameter	Test condition	Symbol	Value	Unit
Collector-emitter voltage		V_{CE}	70	V
Emitter-collector voltage		V_{EC}	7.0	V
Collector current		I_C	50	mA
	$t_p \leq 1.0$ ms	I_C	100	mA
Total power dissipation per channel		P_{diss}	150	mW

Coupler

Parameter	Test condition	Symbol	Value	Unit
Isolation test voltage between emitter and detector (1.0 s)		V_{ISO}	3750	V_{RMS}
Creepage			≥ 5.33	mm
Clearance			≥ 5.08	mm
Comparative tracking index per DIN IEC 112/VDEo 303, part 1			≥ 175	
Isolation resistance	$V_{IO} = 500$ V, $T_{amb} = 25$ °C	R_{IO}	$\geq 10^{12}$	Ω
	$V_{IO} = 500$ V, $T_{amb} = 100$ °C	R_{IO}	$\geq 10^{11}$	Ω
Storage temperature range		T_{stg}	- 55 to + 125	°C
Ambient temperature range		T_{amb}	- 55 to +100	°C
Junction temperature		T_j	100	°C
Soldering temperature	max. 10 s dip soldering distance to seating plane ≥ 1.5 mm		260	°C
Total power dissipation		P_{tot}	70	mW

Electrical Characteristics

$T_{amb} = 25$ °C, unless otherwise specified

Minimum and maximum values are testing requirements. Typical values are characteristics of the device and are the result of engineering evaluation. Typical values are for information only and are not part of the testing requirements.

Input

$T_{amb} = 25$ °C (except where noted)

Parameter	Test condition	Symbol	Min	Typ.	Max	Unit
Forward voltage	$I_F = 5$ mA	V_F		1.15	1.4	V
Reverse current	$V_R = 6.0$ V	I_R		0.01	10	μ A
Capacitance	C_O	C_O		14		pF
Thermal resistance		R_{thja}		1000		K/W

Output

Parameter	Test condition	Symbol	Min	Typ.	Max	Unit
Collector-emitter leakage current	$V_{CE} = 20$ V	I_{CEO}			100	nA
Collector-emitter capacitance	$V_{CE} = 5.0$ V, $f = 1.0$ MHz	C_{CE}		2.8		pF
Thermal resistance		R_{thja}		500		K/W

Coupler

Parameter	Test condition	Symbol	Min	Typ.	Max	Unit
Collector-emitter saturation voltage	$I_F = 20 \text{ mA}$, $I_C = 1.0 \text{ mA}$	V_{CESAT}		0.1	0.4	V
Coupling capacitance	$f = 1.0 \text{ MHz}$	C_C		1.0		pF

Current Transfer Ratio

Parameter	Test condition	Symbol	Min	Typ.	Max	Unit
Current Transfer Ratio	$I_F = 5.0 \text{ mA}$, $V_{CC} = 5.0 \text{ V}$	CTR	50	300		%

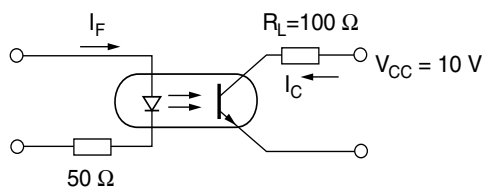
Switching Characteristics

Switching Operation (without saturation)

Parameter	Test condition	Symbol	Min	Typ.	Max	Unit
Rise time	$I_C = 2.0 \text{ mA}$, $V_{CC} = 10 \text{ V}$, $R_L = 100 \Omega$	t_r		4.0		μs
Fall time	$I_C = 2.0 \text{ mA}$, $V_{CC} = 10 \text{ V}$, $R_L = 100 \Omega$	t_f		3.0		μs
Turn on time	$I_C = 2.0 \text{ mA}$, $V_{CC} = 10 \text{ V}$, $R_L = 100 \Omega$	t_{on}		5.0		μs
Turn off time	$I_C = 2.0 \text{ mA}$, $V_{CC} = 10 \text{ V}$, $R_L = 100 \Omega$	t_{off}		4.0		μs

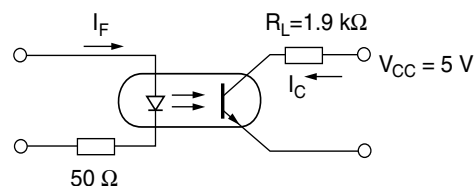
Switching Operation (with saturation)

Parameter	Test condition	Symbol	Min	Typ.	Max	Unit
Rise time	$I_F = 16.0 \text{ mA}$, $V_{CC} = 5.0 \text{ V}$, $R_L = 1.9 \text{ k}\Omega$	t_r		15		μs
Fall time	$I_F = 16.0 \text{ mA}$, $V_{CC} = 5.0 \text{ V}$, $R_L = 1.9 \text{ k}\Omega$	t_f		0.5		μs
Turn on time	$I_F = 16.0 \text{ mA}$, $V_{CC} = 5.0 \text{ V}$, $R_L = 1.9 \text{ k}\Omega$	t_{on}		1.0		μs
Turn off time	$I_F = 16.0 \text{ mA}$, $V_{CC} = 5.0 \text{ V}$, $R_L = 1.9 \text{ k}\Omega$	t_{off}		30		μs



isfh6916_01

Fig. 1 Switching Operation (without Saturation)



isfh6916_02

Fig. 2 Switching Operation (with Saturation)

Typical Characteristics ($T_{amb} = 25^\circ\text{C}$ unless otherwise specified)

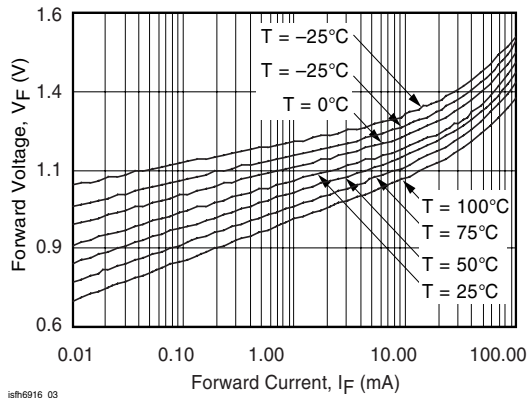


Fig. 3 Diode Forward Voltage vs. Forward Current

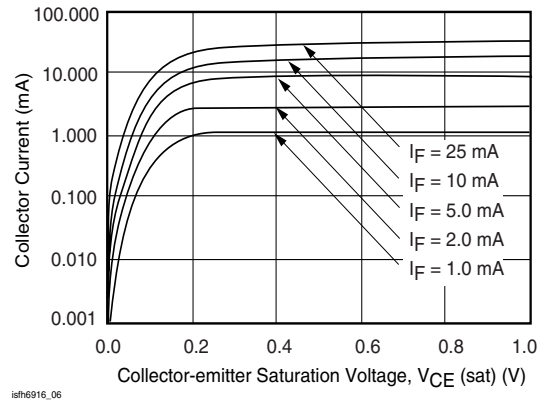


Fig. 6 Collector Current vs. Collector-Emitter Saturation Voltage

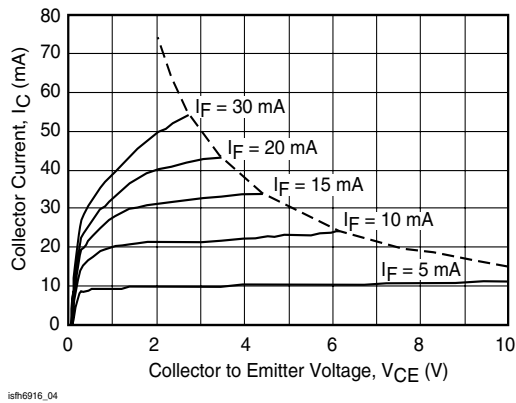


Fig. 4 Collector Current vs. Collector Emitter Voltage

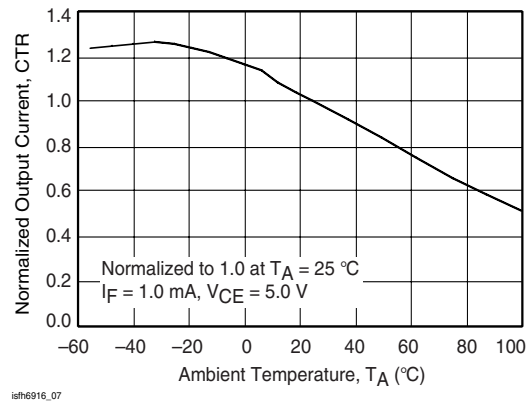


Fig. 7 Normalized Output Current vs. Ambient Temperature

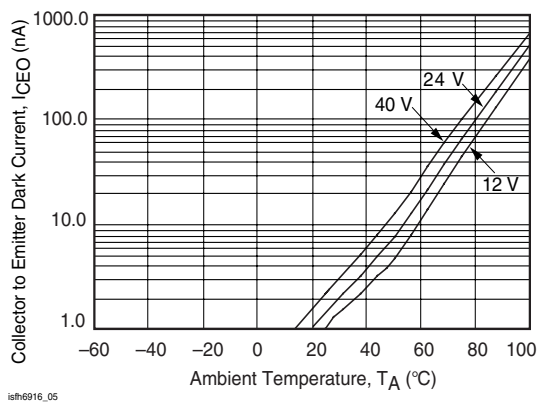


Fig. 5 Collector to Emitter Dark Current vs. Ambient Temperature

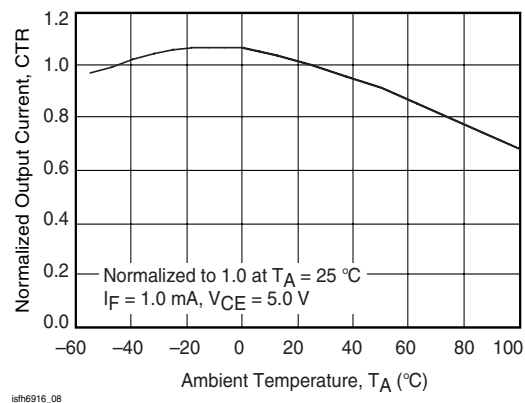


Fig. 8 Normalized Output Current vs. Ambient Temperature

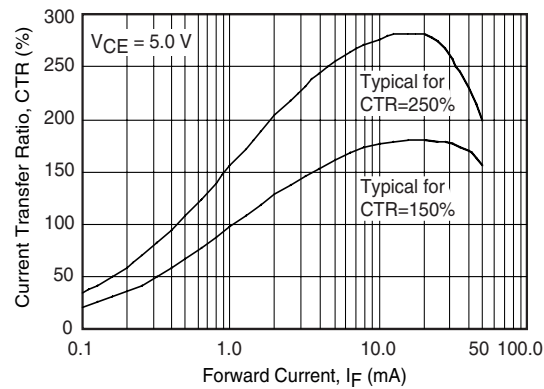


Fig. 9 Current Transfer Ratio vs. Forward Current

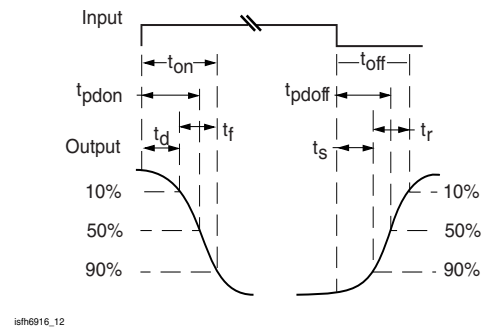


Fig. 12 Switching Time Measurement

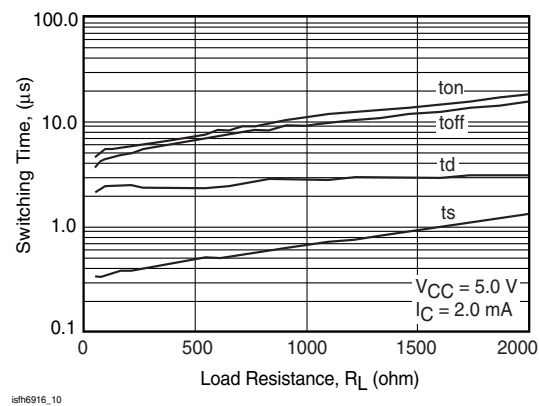


Fig. 10 Switching Time vs. Load Resistance

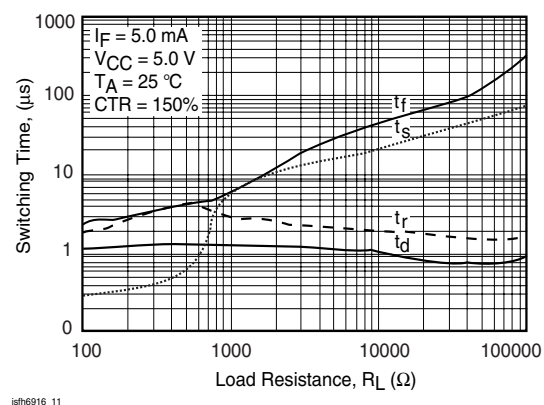
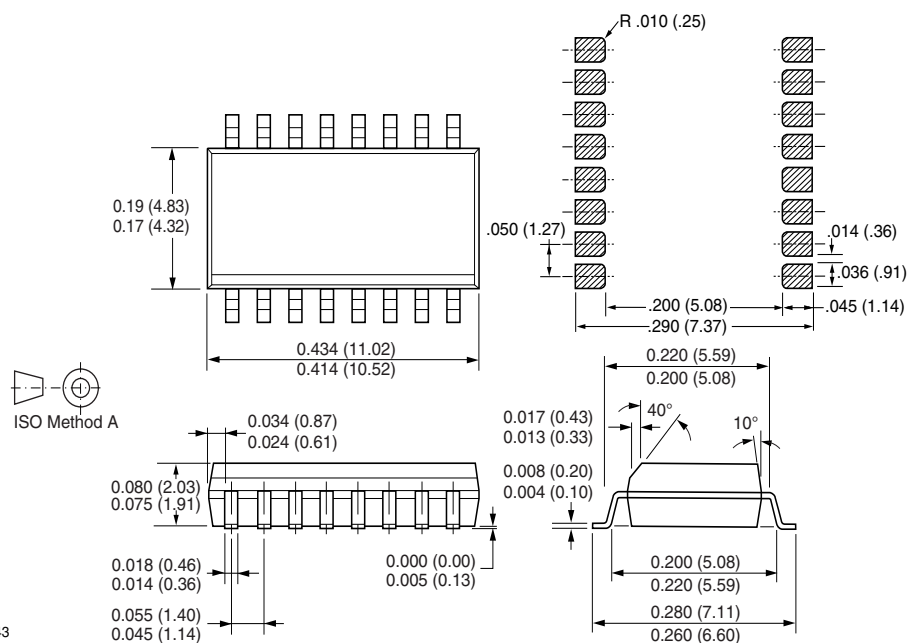


Fig. 11 Switching Time vs. Load Resistance

Package Dimensions in Inches (mm)





Ozone Depleting Substances Policy Statement

It is the policy of **Vishay Semiconductor GmbH** to

1. Meet all present and future national and international statutory requirements.
2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

Vishay Semiconductor GmbH has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively
2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA
3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

Vishay Semiconductor GmbH can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

We reserve the right to make changes to improve technical design and may do so without further notice.

Parameters can vary in different applications. All operating parameters must be validated for each customer application by the customer. Should the buyer use Vishay Semiconductors products for any unintended or unauthorized application, the buyer shall indemnify Vishay Semiconductors against all claims, costs, damages, and expenses, arising out of, directly or indirectly, any claim of personal damage, injury or death associated with such unintended or unauthorized use.

Vishay Semiconductor GmbH, P.O.B. 3535, D-74025 Heilbronn, Germany
Telephone: 49 (0)7131 67 2831, Fax number: 49 (0)7131 67 2423